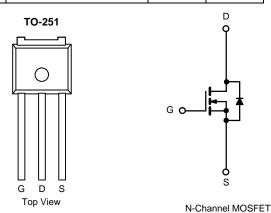


N-Channel 30-V (D-S) MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	$R_{DS(on)}(\Omega)$	I _D (A) ^{a, e}	Q _g (Typ)			
30	0.0035 at V _{GS} = 10 V	100	95nC			
	0.0045 at $V_{CS} = 4.5$ V	97	95110			



FEATURES

- TrenchFET® Power MOSFET
- 100 % R_g and UIS Tested
 Compliant to RoHS Directive 2011/65/EU



APPLICATIONS

- OR-ing
- Server
- DC/DC

Parameter	Symbol	Limit	Unit		
Drain-Source Voltage	V _{DS}	30	V		
Gate-Source Voltage		V _{GS}		± 20	
	T _C = 25 °C		100 ^{a, e}	A	
Continuous Drain Current (T _{.I} = 175 °C)	T _C = 70 °C		95 ^e		
Continuous Diam Current (1 _J = 175 C)	T _A = 25 °C	I _D	35 ^{b, c}		
	T _A = 70 °C		26 ^{b, c}		
Pulsed Drain Current		I _{DM}	197		
Avalanche Current Pulse	L = 0.1 mH	I _{AS}	39		
Single Pulse Avalanche Energy	L = 0.1 IIII	E _{AS}	94.8	mJ	
Continuous Source-Drain Diode Current	T _C = 25 °C	I.	90 ^{a, e}	^	
Continuous Source-Diam Diode Current	T _A = 25 °C	I _S	3.13 ^{b, c}	Α	
	T _C = 25 °C		250 ^a		
Maximum Dawar Dingingtion	T _C = 70 °C	P _D	175	١٨/	
Maximum Power Dissipation	T _A = 25 °C	' D	3.75 ^{b, c}	W	
	T _A = 70 °C		2.63 ^{b, c}		
Operating Junction and Storage Temperature Ra	T _J , T _{stg}	- 55 to 175	°C		

THERMAL RESISTANCE RATINGS							
Parameter	Symbol	Тур.	Max.	Unit			
Maximum Junction-to-Ambient ^{b, d}	t ≤ 10 sec	R_{thJA}	32	40	°C/W		
Maximum Junction-to-Case	Steady State	R _{thJC}	0.5	0.6	C/VV		

Notes:

- a. Based on T_C = 25 °C.
 b. Surface mounted on 1" x 1" FR4 board.

- b. Striate informed on 1 X 1 114 board.
 c. t = 10 sec.
 d. Maximum under steady state conditions is 90 °C/W.
 e. Calculated based on maximum junction temperature. Package limitation current is 90 A.



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V, I}_{D} = 250 \mu\text{A}$	30			V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I _D = 250 μA		35		mV/°C
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	1 _D = 230 μΑ		- 7.5		
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1.0		2.5	V
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 30 V, V _{GS} = 0 V			1	, . ^
		V _{DS} = 30 V, V _{GS} = 0 V, T _J = 55 °C			10	μA
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	90			Α
		V _{GS} = 10 V, I _D = 38.8 A		0.0035		
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = 4.5 \text{ V}, I_D = 37 \text{ A}$	0.0045			Ω
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 38.8 A		160		S
Dynamic ^b				'		
Input Capacitance	C _{iss}			3000		pF
Output Capacitance	C _{oss}	$V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		710		
Reverse Transfer Capacitance	C _{rss}			170		
Total Gate Charge	0	$V_{DS} = 15 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 38.8 \text{ A}$		171	257	nC
	Qg			81.5	123	
Gate-Source Charge	Q _{gs}	$V_{DS} = 15 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 28.8 \text{ A}$		34		
Gate-Drain Charge	Q_{gd}			29		
Gate Resistance	R _g	f = 1 MHz		1.4	2.1	Ω
Turn-On Delay Time	t _{d(on)}			18	27	-
Rise Time	t _r	V_{DD} = 15 V, R_L = 0.625 Ω		11	17	
Turn-Off Delay Time	t _{d(off)}	$I_D\cong 24$ A, V_{GEN} = 10 V, R_g = 1 Ω		70	105	
Fall Time	t _f			10	15	
Turn-On Delay Time	t _{d(on)}			55	83	ns
Rise Time	t _r	V_{DD} = 15 V, R_L = 0.67 Ω		180	270	- - -
Turn-Off Delay Time	t _{d(off)}	$I_D\cong 22.5$ A, V_{GEN} = 4.5 V, R_g = 1 Ω		55	83	
Fall Time	t _f			12	18	
Drain-Source Body Diode Characteristic	s			'		
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C			120	۸
Pulse Diode Forward Current ^a	I _{SM}				120	Α
Body Diode Voltage	V _{SD}	I _S = 22 A		0.8	1.2	V
Body Diode Reverse Recovery Time	t _{rr}			52	78	ns
Body Diode Reverse Recovery Charge	Q _{rr}			70.2	105	nC
Reverse Recovery Fall Time	t _a	$I_F = 20 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 \text{ °C}$		27		
Reverse Recovery Rise Time	t _b			25		ns

Notes:

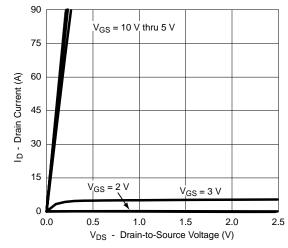
- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

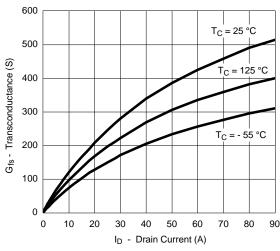
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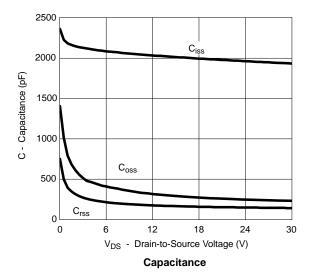
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

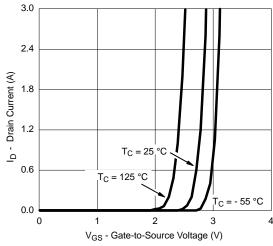


Output Characteristics

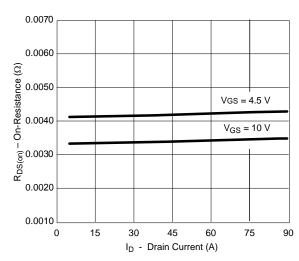


Transconductance

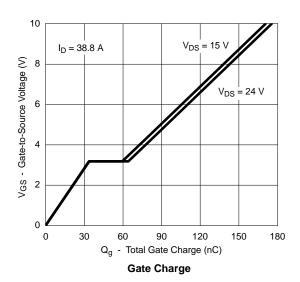




Transfer Characteristics



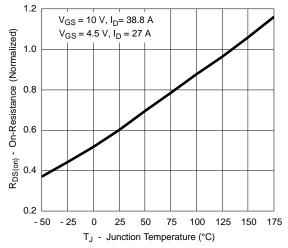
R_{DS(on)} vs. Drain Current



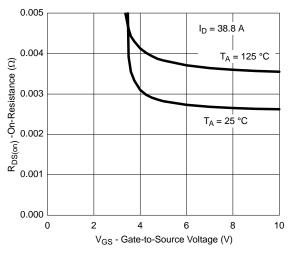
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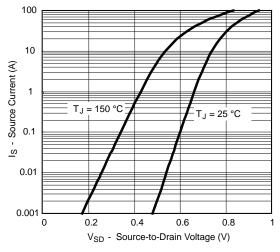
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



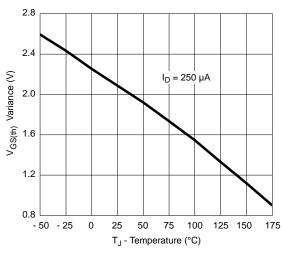
On-Resistance vs. Junction Temperature



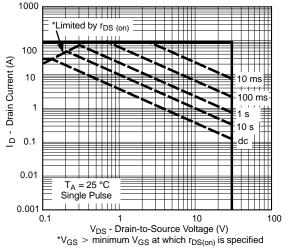
 $R_{DS(on)}\, vs.\, V_{GS}\, vs.\, Temperature$



Forward Diode Voltage vs. Temperature



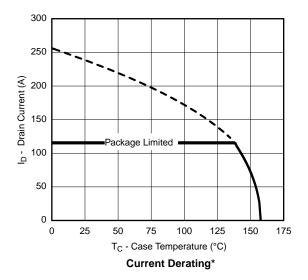
Threshold Voltage

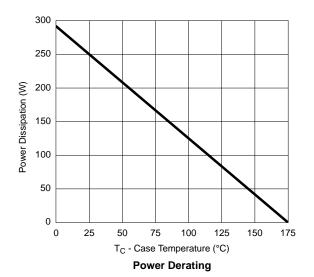


Safe Operating Area, Junction-to-Ambient

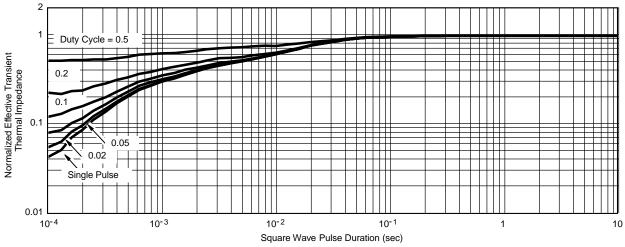


TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)





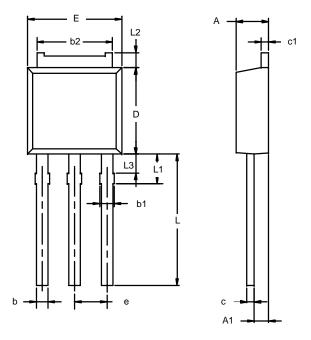
*The power dissipation P_D is based on $T_{J(max)}$ = 175 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



Normalized Thermal Transient Impedance, Junction-to-Case



TO-251AA (DPAK)



Note: Dimension L3 is for reference only.

	MILLIM	IETERS	INCHES			
Dim	Min	Max	Min	Max		
Α	2.21	2.38	0.087	0.094		
A 1	0.89	1.14	0.035	0.045		
b	0.71	0.89	0.028	0.035		
b1	0.76	1.14	0.030	0.045		
b2	5.23	5.43	0.206	0.214		
С	0.46	0.58	0.018	0.023		
с1	0.46	0.58	0.018	0.023		
D	5.97	6.22	0.235	0.245		
Е	6.48	6.73	0.255	0.265		
е	2.28	BSC	0.090 BSC			
L	8.89	9.53	0.350	0.375		
L1	1.91	2.28	0.075	0.090		
L2	0.89	1.27	0.035	0.050		
L3	1.15	1.52	0.045	0.060		
ECN: S-03946—Rev. E, 09-Jul-01 DWG: 5346						

服务热线:400-655-8788



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DMN2080UCB4-7 DMN61D9UWQ-13 US6M2GTR DMN31D5UDJ-7 DMP22D4UFO-7B DMN1006UCA6-7 DMN16M9UCA6-7
STF5N65M6 IRF40H233XTMA1 STU5N65M6 DMN6022SSD-13 DMN13M9UCA6-7 DMTH10H4M6SPS-13 DMN2990UFB-7B
IPB80P04P405ATMA2 2N7002W-G MCAC30N06Y-TP MCQ7328-TP BXP7N65D BXP4N65F AOL1454G WMJ80N60C4 BXP2N20L
BXP2N65D BXT1150N10J BXT1700P06M TSM60NB380CP ROG RQ7L055BGTCR DMNH15H110SK3-13 SLF10N65ABV2
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